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IN THE UNITED STATES PATENT OFFICE

Serial No.: ~~Unassigned~~ 09/831763

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For: METHOD OF ELECTROLYTICALLY FORMING CONDUCTOR  
STRUCTURES FROM HIGHLY PURE COPPER WHEN PRODUCING  
INTEGRATED SYSTEMS

Inventor: Heinrich Meyer, Andreas Thies

Atty Doc. No.: 71-01

**INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In the interest of full disclosure, the following items are herewith identified in Form PTO-1449 and a copy of the same is hereby provided, for the convenience of the U.S. Patent and Trademark Office.

This Information Disclosure Statement is being filed before the mailing date of the first official action.

**FOREIGN PATENT**

(AA) DE 195 45 231 A1 Heinrich Meyer, dated May 22, 1997. Relevance is that it was cited in the PCT Preliminary Examination Report as a category A reference for claims 1, 2 and 4-9 as the general state of the art.

**OTHER DOCUMENTS**

(AB) J.W. Chang, P.C. Andricacos, B. Petek and L.T. Romankiw  
ELECTRODEPOSITION OF HIGH M, CoFeCu ALLOYS FOR RECORDING  
HEADS  
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IBM Research Division, T.J. Watson Research Center

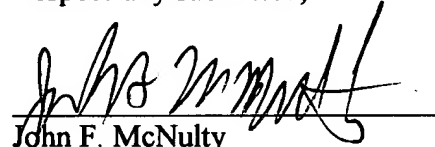
(AC) L.T. Romankiw, pH CHANGES AT THE CATHODE DURING ELECTROLYSIS  
OF Ni, Fe, Cu and THEIR ALLOYS AND A SIMPLE TECHNIQUE FOR  
MEASURING pH CHANGES AT THE ELECTRODES  
1987, Pages 301-325  
IBM, T.J. Watson Research Center

(AD) P.C. Andricacos, C Uzoh, J.O. Dukovic, J. Horkans, H. Deligianni  
IBM JOURNAL OF RESEARCH AND DEVELOPMENT VOLUME  
September 1998, Pages 567-574

(AE) Linda Geppert  
SOLID STATE  
January 1998, Pages 23-28

(AF) A. RIESENKAMPF, et al.,  
STUDIES ON THE PREPARATION AND PROPERTIES OF  
ELECTRODEPOSITED NICKEL-IRON AND NICKEL-COBALT MAGNETIC  
FILMS  
1975, Pages 377-38. Relevance is electroplating of a perm-alloy (Ni/Fe-alloy) is  
described. For electroplating the alloy a plating bath is used containing iron at a  
content of 15 g/l  $\text{FeSO}_4 \cdot 7\text{H}_2\text{O}$  which is essentially same as the iron concentration in the  
copper plating bath according to the invention. Electroplating from this relating bath  
would lead to a considerable iron content in the alloy.

Respectfully submitted,



John F. McNulty

Reg. No. 23,028

Attorney for Applicants

Paul & Paul

2900 Two Thousand Market St.

Philadelphia, PA 19103

(215) 568-4900